

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

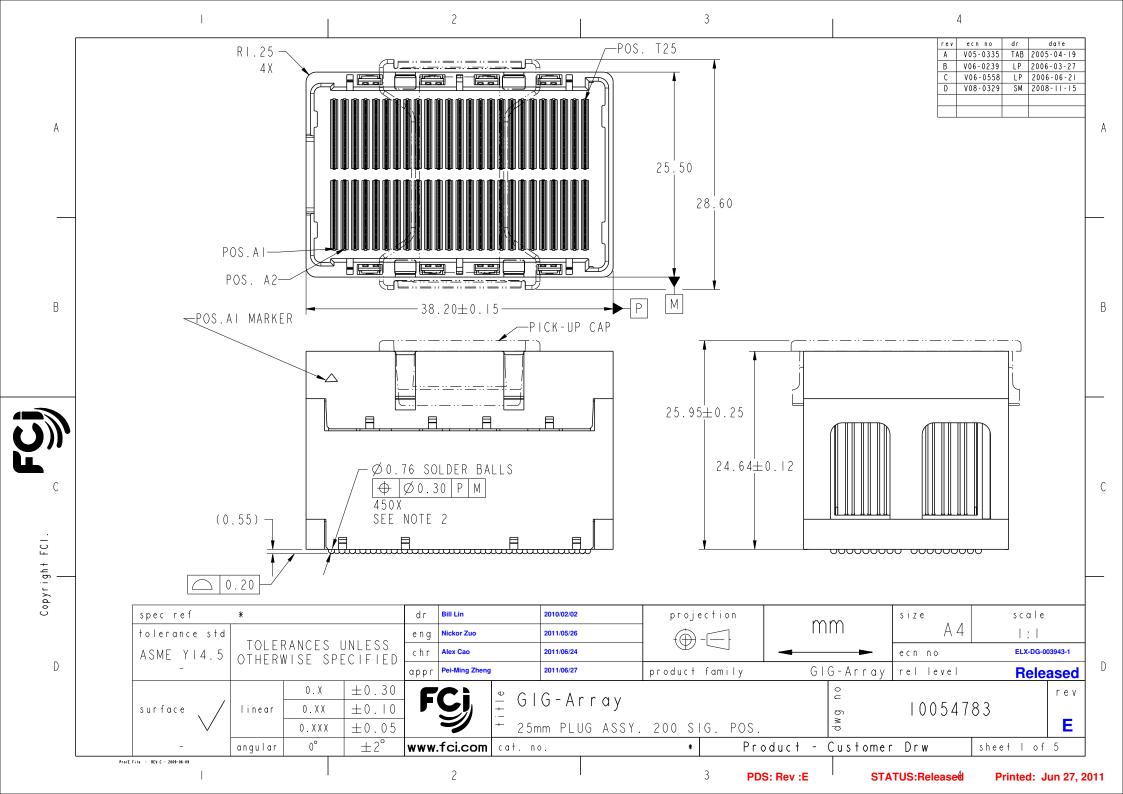
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

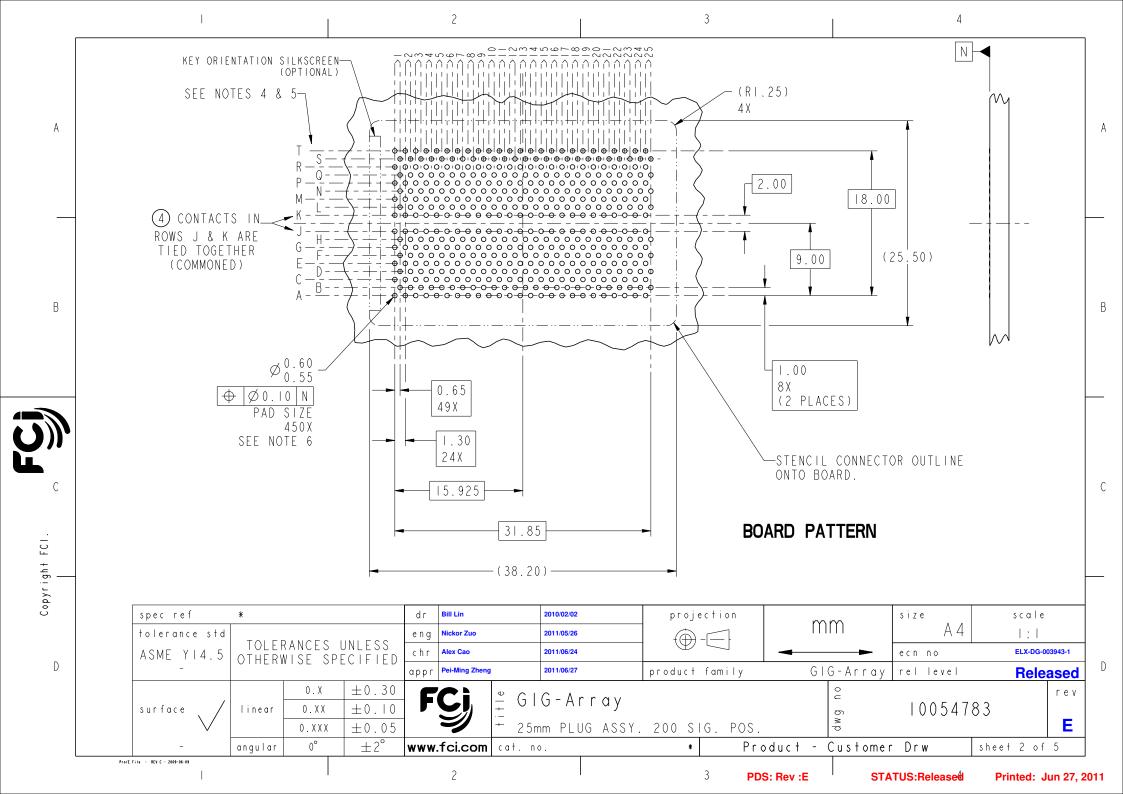
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

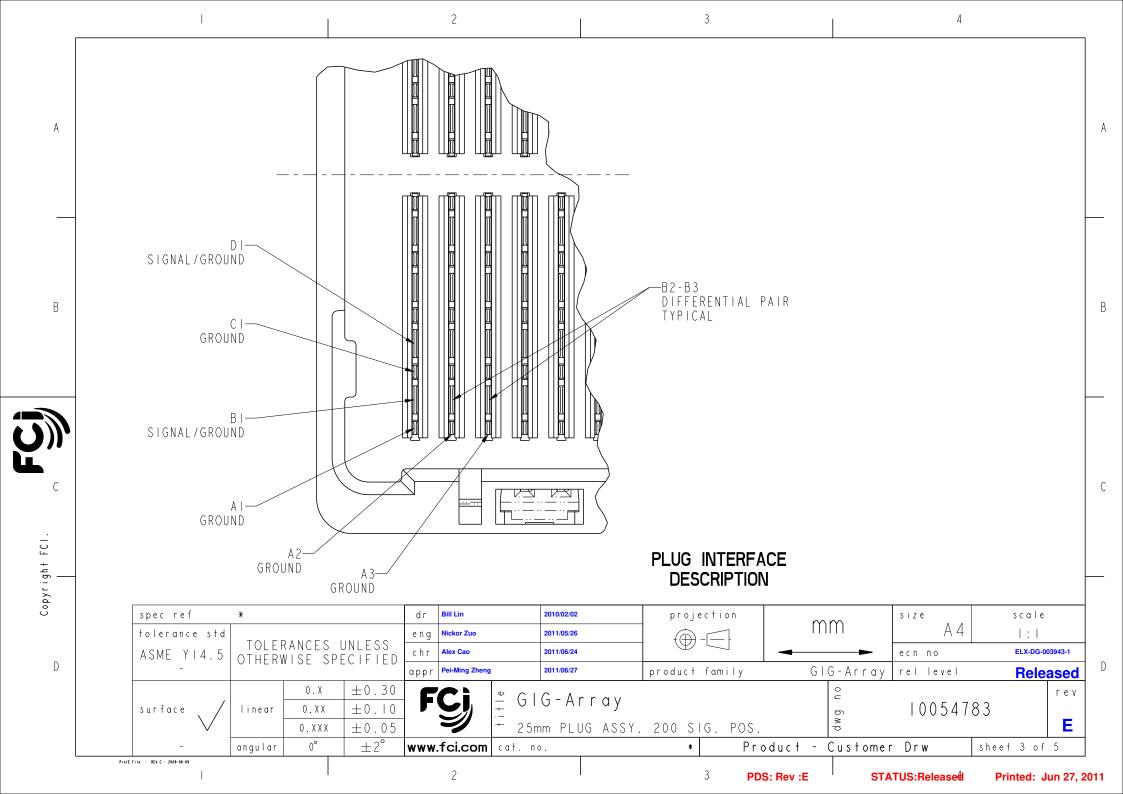


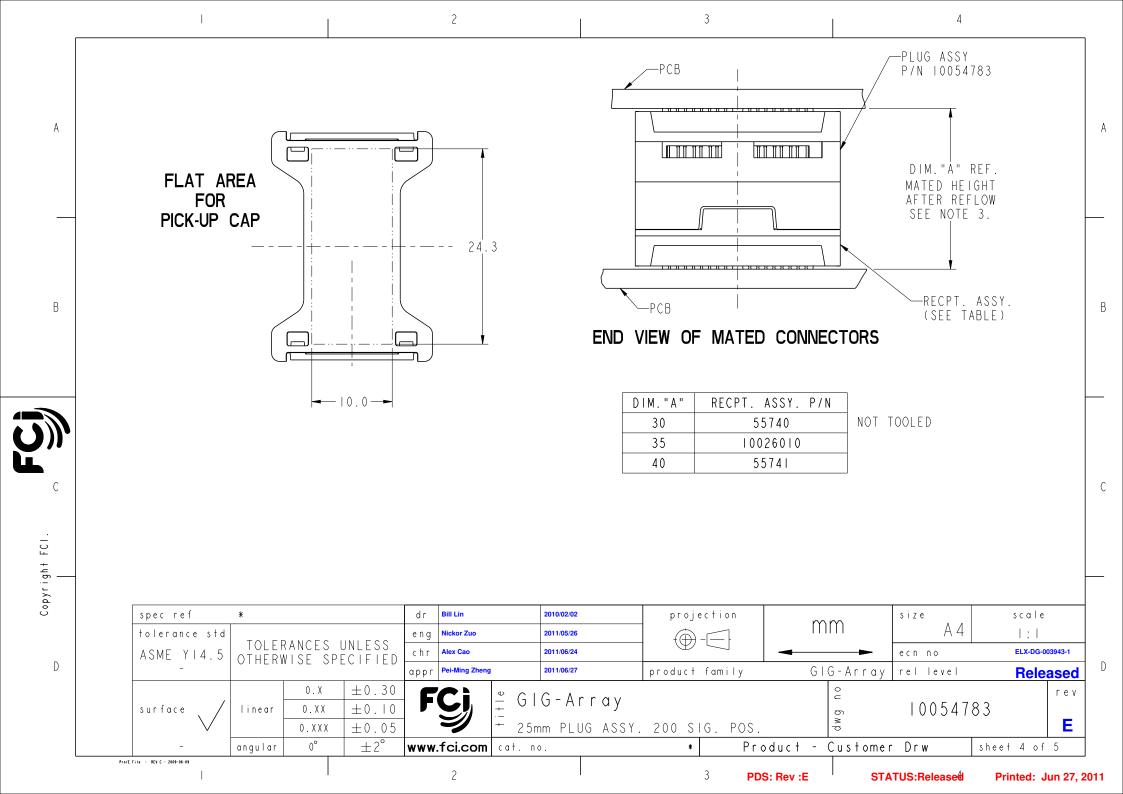












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NOTES:

MAT'L:

HOUSING: LCP
CONTACT: COPPER ALLOY
PLATING (CONTACT): Au OVER Ni.
UL RATING: 94 V-O
SOLDER BALL: (SEE TABLE) EUTECTIC
SnPb OR LEADFREE 95.5 Sn/4Ag/0.5Cu

2) SOLDER BALLS WILL NOT BE PERFECT SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.

- (3) MATED HEIGHT EFFECTED BY CUSTOMERS'
 PCB PAD SIZE, PLATING, SOLDER REFLOW
 PROFILE & SOLDER PASTE.
- 4 CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T ARE SINGLE BEAM CONTACTS, TYPICALLY USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])

- 5. CONTACTS IN ROWS B,D,F,H,L,N,Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.
- 6 SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE DOC. NO. GS-20-016.
- 7. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEADFREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE, LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS, REFERENCE FCI APPLICATION SPECIFICATION.
- 8. THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN HTE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

spec ref dr Bill Lin 2010/02/02 projection size scale mm A 4 tolerance std eng Nickor Zuo 2011/05/26 1:1 TOLERANCES UNLESS ELX-DG-003943-1 chr Alex Cao 2011/06/24 ASME YI4.5 ecn no OTHERWISE SPECIFIED 2011/06/27 Pei-Ming Zheng product family GIG-Array rel level appr Released ± 0.30 0 U 0.X rev GIG-Array 10054783 linear 0.XX ± 0.10 surface D Ε ± 0.05 25mm PLUG ASSY, 200 SIG, POS, 0.XXX $\pm 2^{\circ}$ 0° www.fci.com | cat. no. sheet 5 of 5 angular Product - Customer Drw

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D

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Pro/E File - REV C - 2009-06-09

PDS: Rev :E

STATUS:Released

Printed: Jun 27, 2011